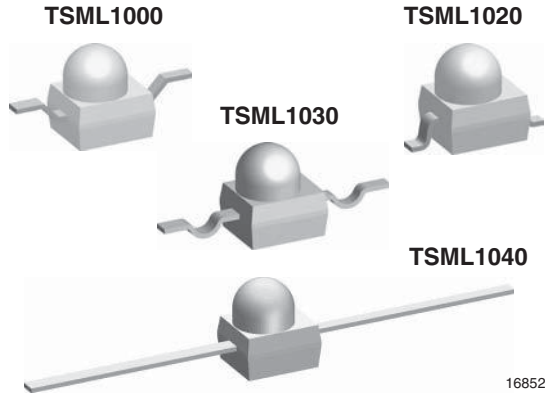




## High Power Infrared Emitting Diode, RoHS Compliant, 940 nm, GaAlAs/GaAs



16852

### FEATURES

- Package type: surface mount
- Package form: GW, RGW, yoke, axial
- Dimensions (L x W x H in mm): 2.5 x 2 x 2.7
- Peak wavelength:  $\lambda_p = 940 \text{ nm}$
- High radiant power
- High radiant intensity
- Angle of half intensity:  $\phi = \pm 12^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Good spectral matching with Si photodetectors
- Versatile terminal configurations
- Package matches with detector TEMT1000
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Compliant to RoHS Directive 2002/95/EC and in accordance with WEEE 2002/96/EC



RoHS COMPLIANT

### DESCRIPTION

TSML1000 is an infrared, 940 nm emitting diode in GaAlAs/GaAs with high radiant power molded in a clear, untinted plastic package (with lens) for surface mounting (SMD).

### APPLICATIONS

- For remote control
- Punched tape readers
- Encoder
- Photointerrupters

PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr)	$\phi$ (deg)	$\lambda_p$ (nm)	$t_r$ (ns)
TSML1000	7	$\pm 12$	940	800
TSML1020	7	$\pm 12$	940	800
TSML1030	7	$\pm 12$	940	800
TSML1040	7	$\pm 12$	940	800

#### Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TSML1000	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing
TSML1020	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing
TSML1030	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Yoke
TSML1040	Bulk	MOQ: 1000 pcs, 1000 pcs/bulk	Axial leads

#### Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100\text{ }\mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	$I_{FSM}$	1.0	A
Power dissipation		$P_V$	190	mW
Junction temperature		$T_j$	100	$^{\circ}\text{C}$
Operating temperature range		$T_{amb}$	- 40 to + 85	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	- 40 to + 100	$^{\circ}\text{C}$
Soldering temperature	$t \leq 5\text{ s}$	$T_{sd}$	< 260	$^{\circ}\text{C}$
Thermal resistance junction/ambient	Soldered on PCB, pad dimensions: 4 mm x 4 mm	$R_{thJA}$	400	$^{\circ}\text{C}$

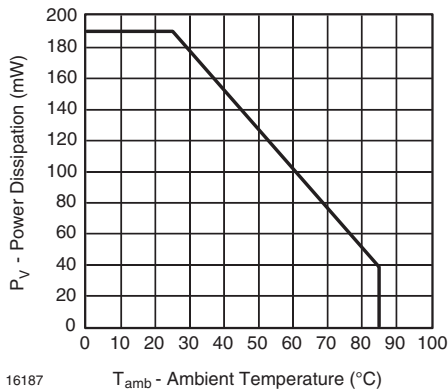


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

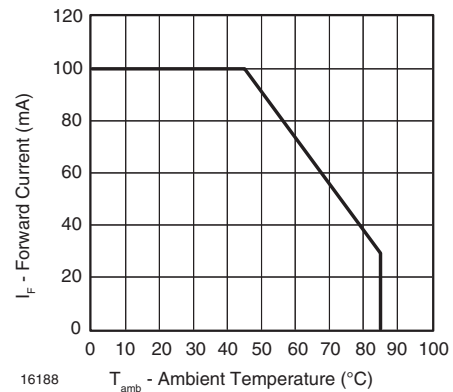


Fig. 2 - Forward Current vs. Ambient Temperature

BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 20\text{ mA}, t_p = 20\text{ ms}$	$V_F$		1.2	1.5	V
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	$V_F$		2.6		V
Temperature coefficient of $V_F$	$I_F = 1\text{ mA}$	$TK_{V_F}$		- 1.8		mV/K
Reverse current	$V_R = 5\text{ V}$	$I_R$			10	$\mu\text{A}$
Junction capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0$	$C_j$		25		pF
Radiant intensity	$I_F = 20\text{ mA}, t_p = 20\text{ ms}$	$I_e$	3	7	15	mW/sr
Radiant power	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$\phi_e$		35		mW
Temperature coefficient of $\phi_e$	$I_F = 20\text{ mA}$	$TK_{\phi_e}$		- 0.6		%/K
Angle of half intensity		$\varphi$		$\pm 12$		deg
Peak wavelength	$I_F = 100\text{ mA}$	$\lambda_p$		940		nm
Spectral bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$		50		nm
Temperature coefficient of $\lambda_p$	$I_F = 100\text{ mA}$	$TK_{\lambda_p}$		0.2		nm/K
Rise time	$I_F = 100\text{ mA}$	$t_r$		800		ns
Fall time	$I_F = 100\text{ mA}$	$t_f$		800		ns
Virtual source diameter		$d$		1.2		mm



## BASIC CHARACTERISTICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

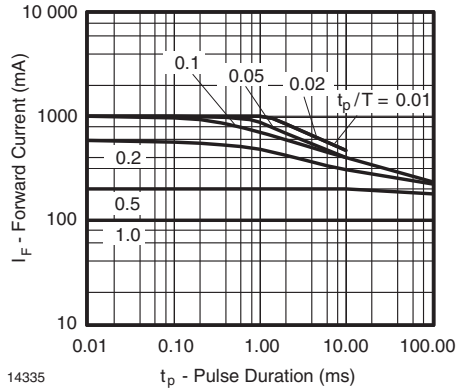


Fig. 3 - Pulse Forward Current vs. Pulse Duration

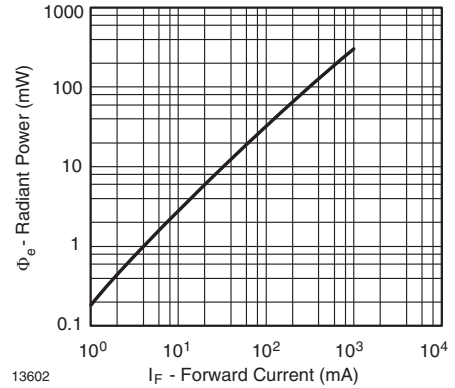


Fig. 6 - Radiant Power vs. Forward Current

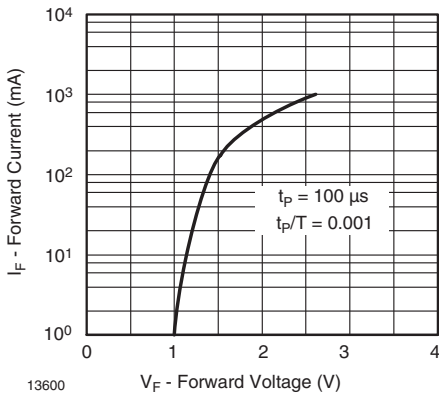


Fig. 4 - Forward Current vs. Forward Voltage

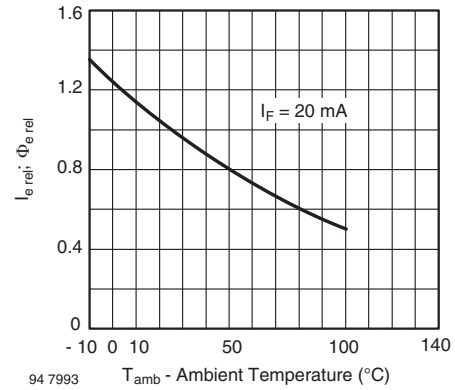


Fig. 7 - Relative Radiant Intensity/Power vs. Ambient Temperature

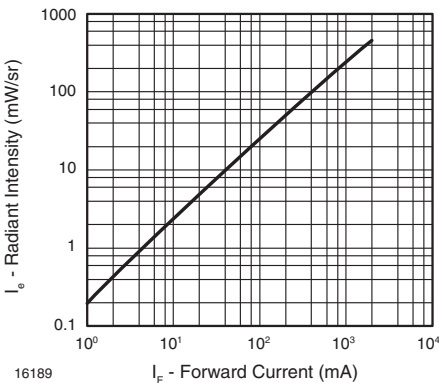


Fig. 5 - Radiant Intensity vs. Forward Current

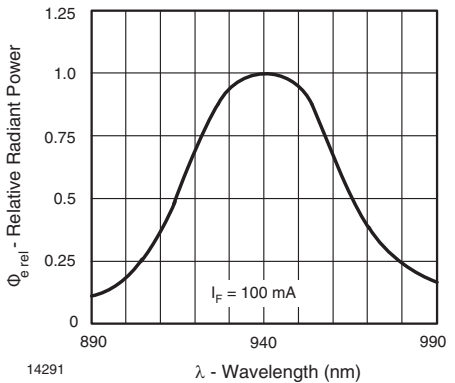


Fig. 8 - Relative Radiant Power vs. Wavelength

**REFLOW SOLDER PROFILE**

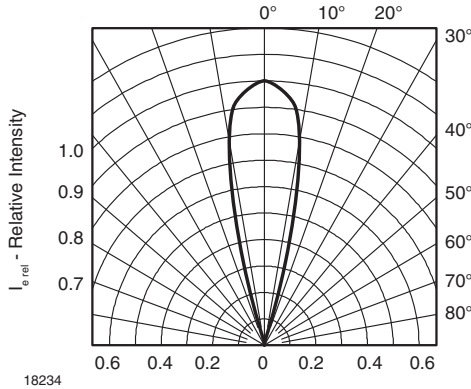


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

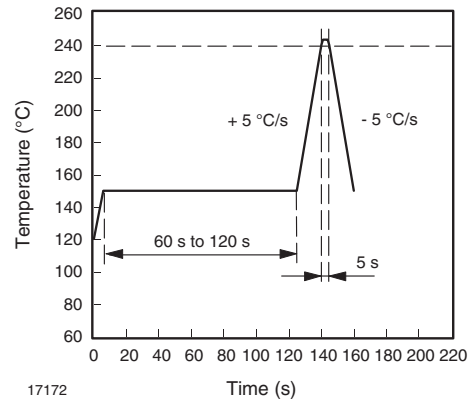


Fig. 10 - Lead Tin (SnPb) Reflow Solder Profile

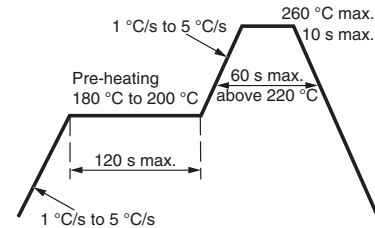
**PRECAUTIONS FOR USE**

**1. Over-current-proof**

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (burn out will happen).

**2. Storage**

- 2.1 Storage temperature and rel. humidity conditions are: 5 °C to 35 °C, R.H. 60 %.
- 2.2 Floor life must not exceed 168 h, acc. to JEDEC level 3, J-STD-020.  
Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccant. Considering tape life, we suggest to use products within one year from production date.
- 2.3 If opened more than one week in an atmosphere 5 °C to 35 °C, R.H. 60 %, devices should be treated at 60 °C ± 5 °C for 15 h.
- 2.4 If humidity indicator in the package shows pink color (normal blue), then devices should be treated with the same conditions as 2.3.

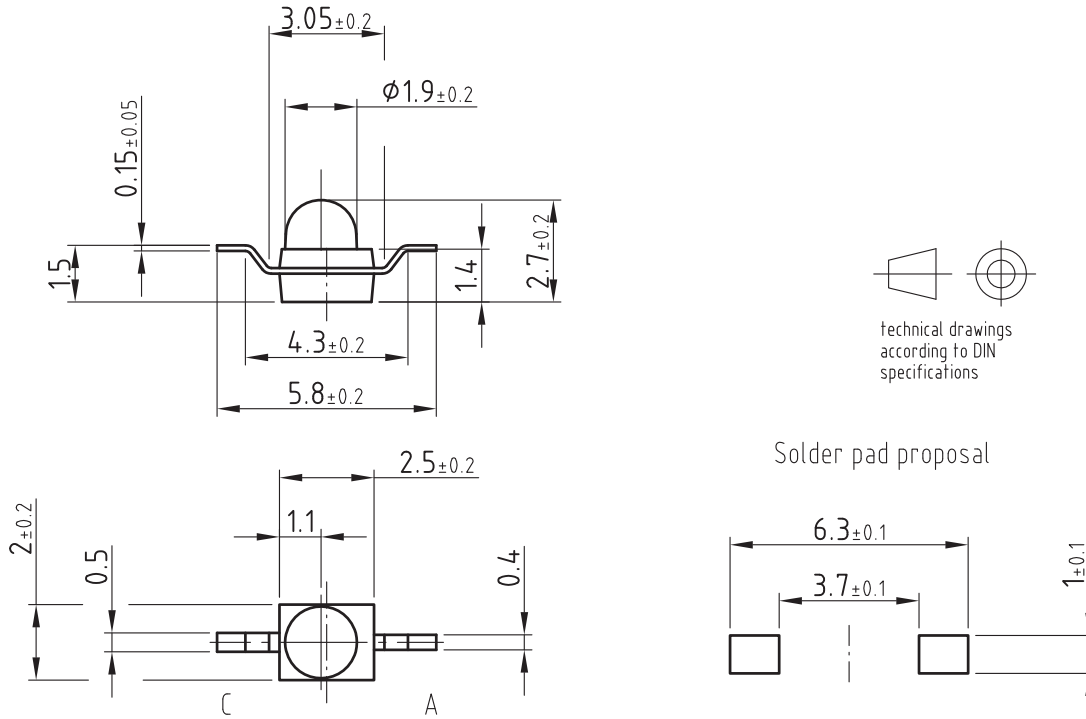


22566

Fig. 11 - Lead (Pb)-Free Reflow Solder Profile acc. J-STD-020

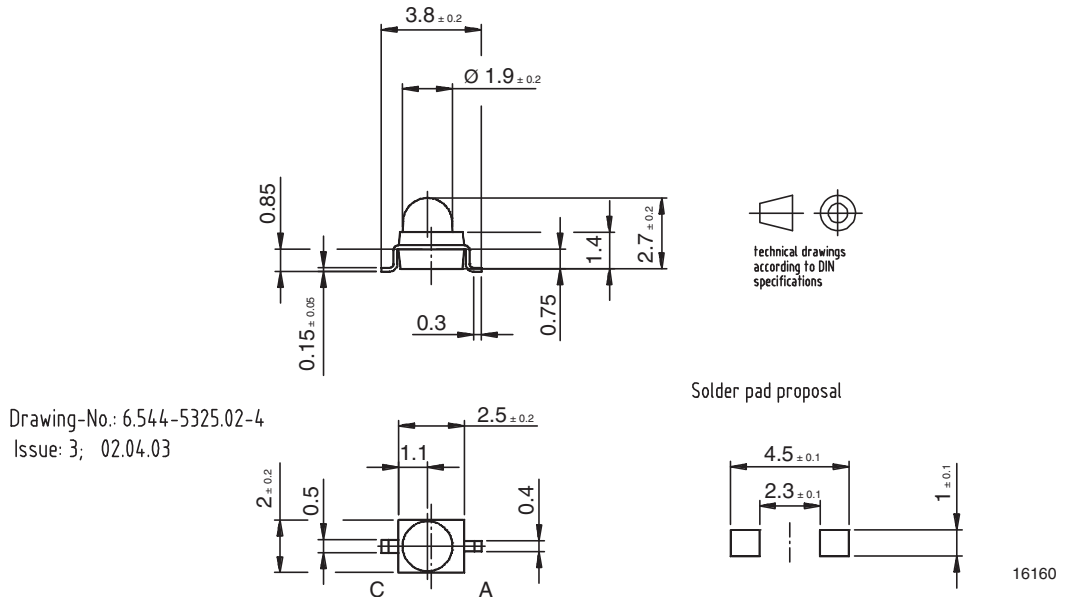


## PACKAGE DIMENSIONS in millimeters: TSML1000



Drawing-No.: 6.544-5326.02-4  
 Issue: 3; 02.04.03  
 16159

## PACKAGE DIMENSIONS in millimeters: TSML1020

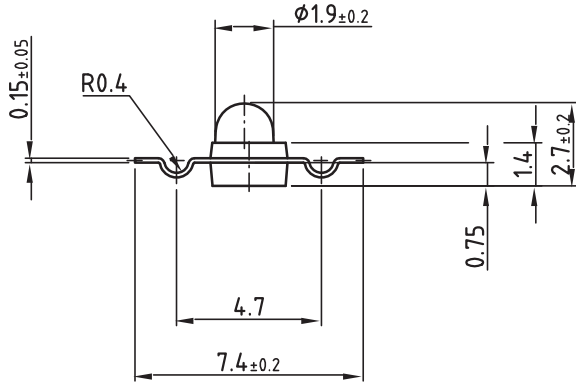


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 Issue: 3; 02.04.03

16160

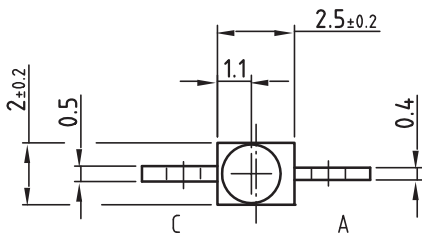
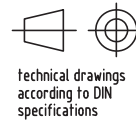


## PACKAGE DIMENSIONS in millimeters: TSML1030

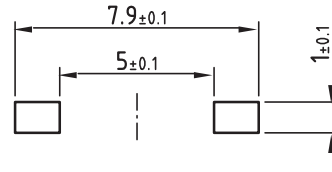


Drawing-No.: 6.544-5329.01-4

Issue: 4; 08.05.03

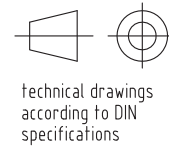
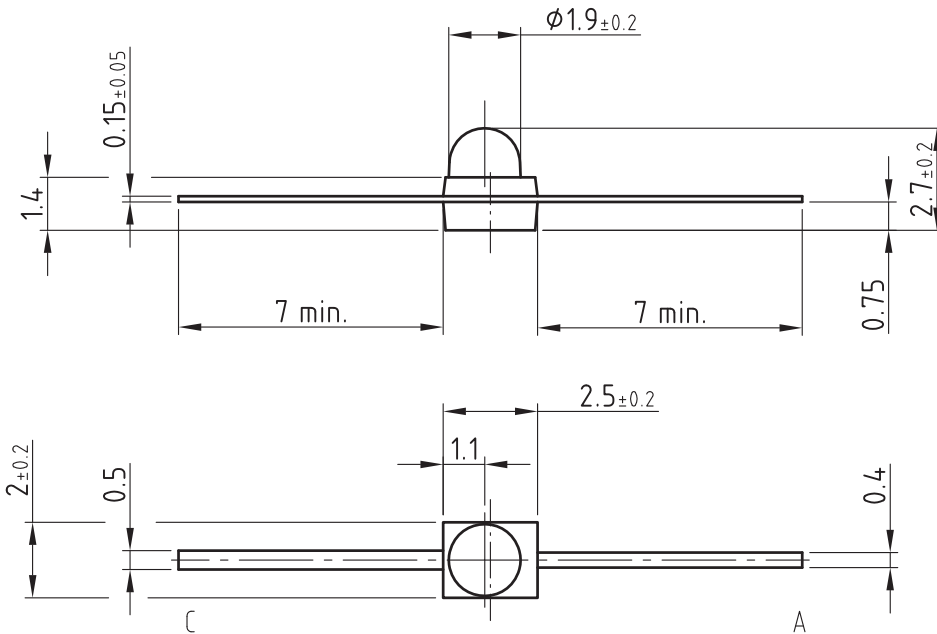


Solder pad proposal



16228

## PACKAGE DIMENSIONS in millimeters: TSML1040



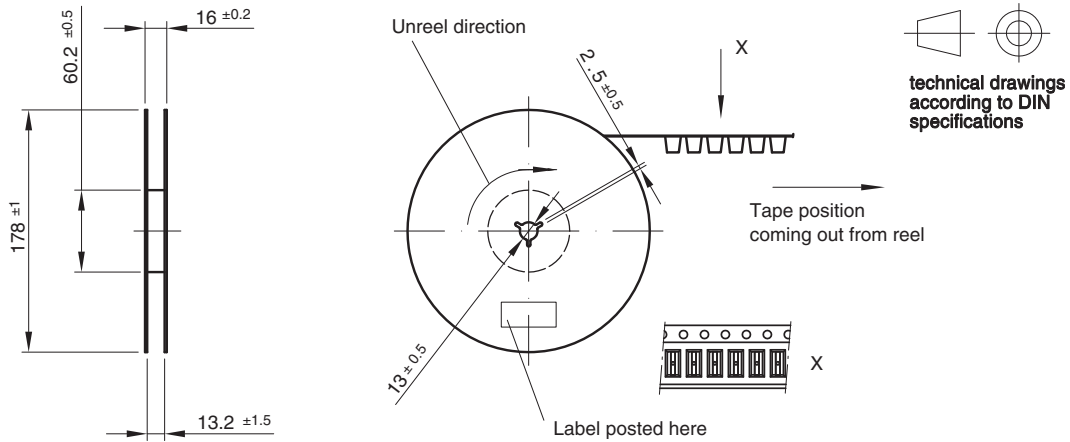
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Issue: 3; 02.04.03

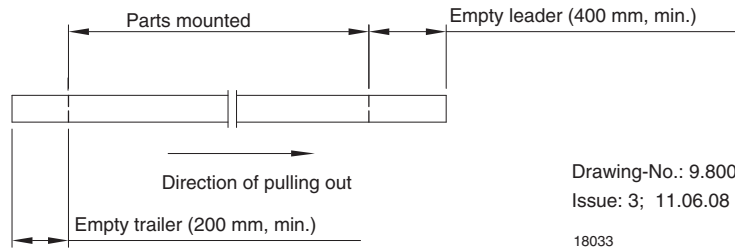
16760



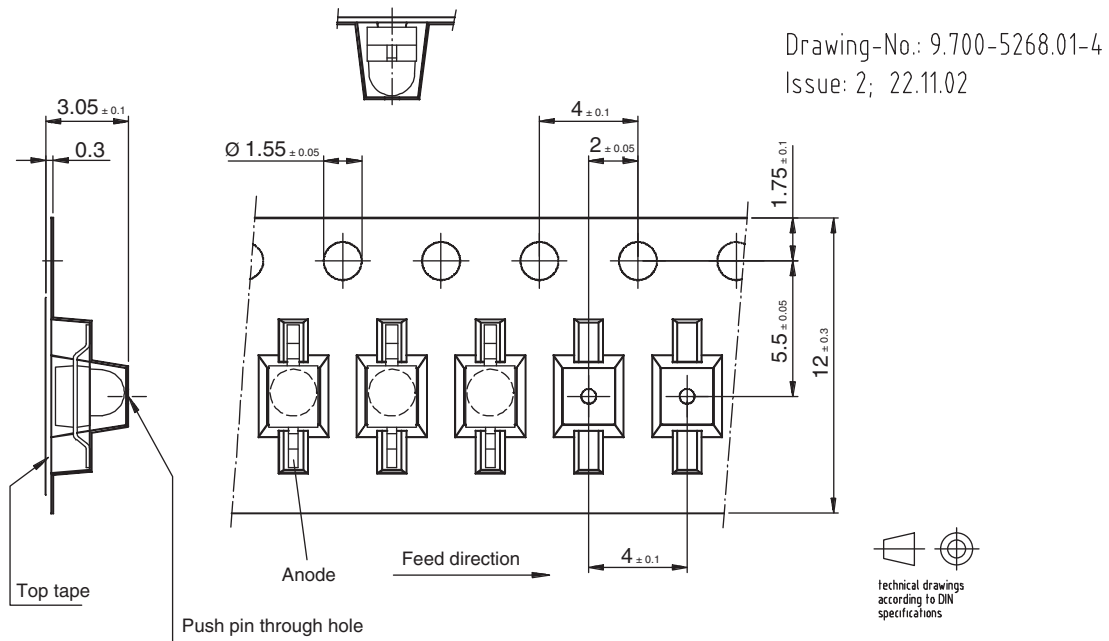
## REEL DIMENSIONS in millimeters



### Leader and trailer tape:



## TAPING DIMENSIONS in millimeters: TSML1000

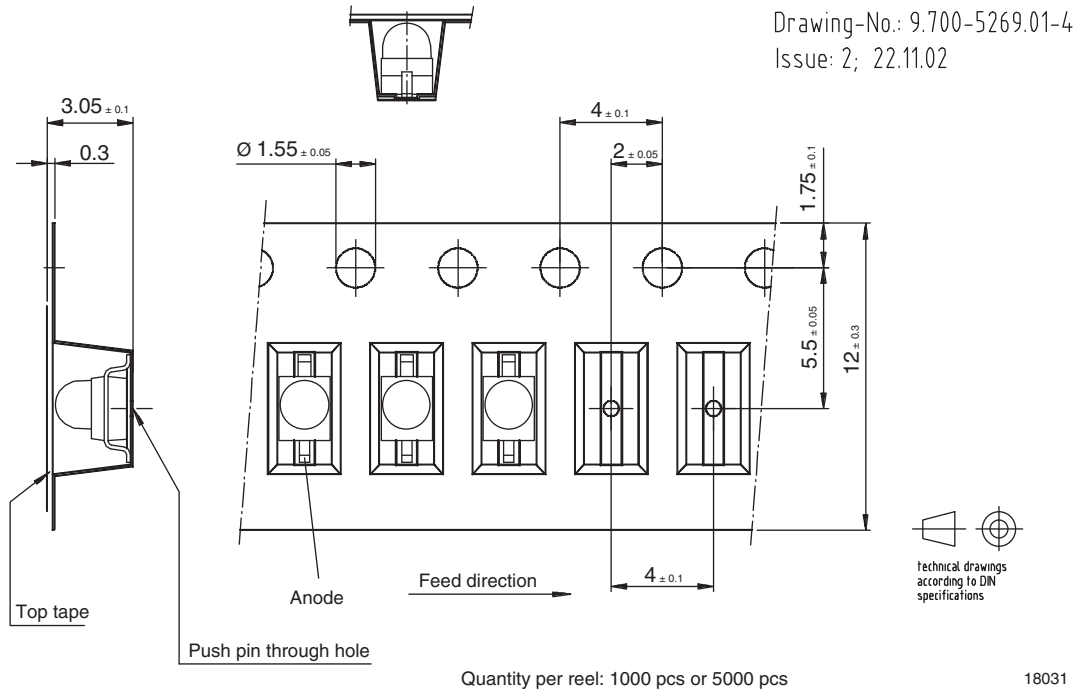


Quantity per reel: 1000 pcs or 5000 pcs

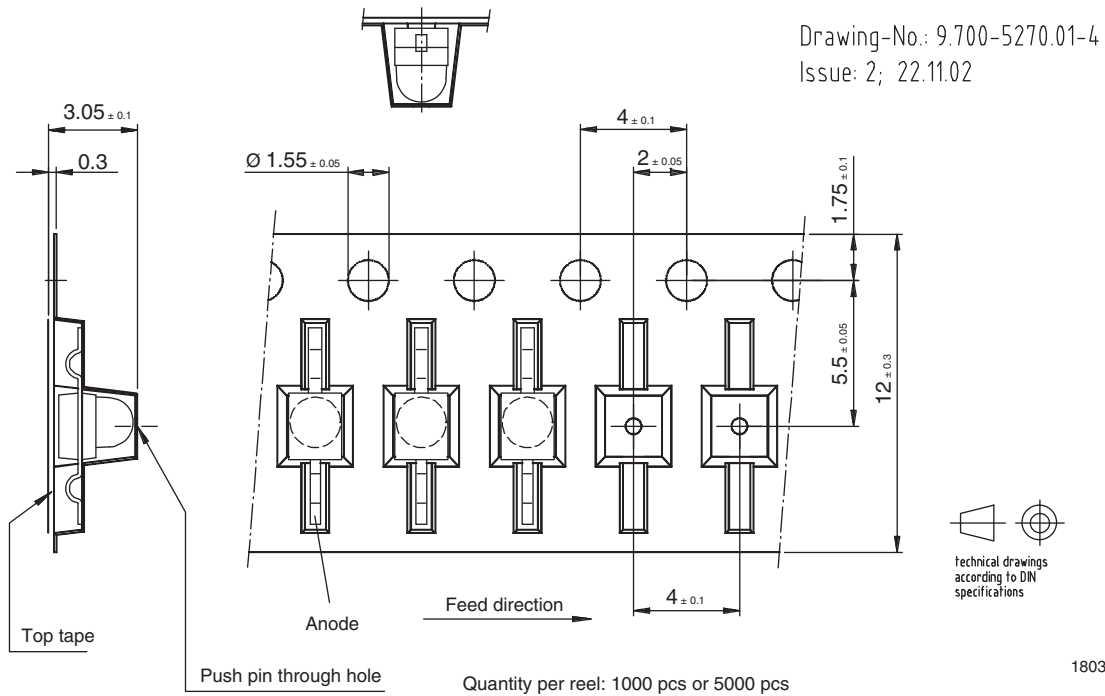
18030



## TAPING DIMENSIONS in millimeters: TSML1020



## TAPING DIMENSIONS in millimeters: TSML1030







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### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

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